

L Number	Hits	Search Text	DB	Time stamp
1	1573	(250/281,282).CCLS.	USPAT; US-PGPUB	2003/11/25 10:49
2	783	(438/745).CCLS.	USPAT; US-PGPUB	2003/11/25 10:49
3	884	(436/43,47).CCLS.	USPAT; US-PGPUB	2003/11/25 10:49
4	3944	(134/2,10,22.14,32,48,71,79,80).CCLS.	USPAT; US-PGPUB	2003/11/25 10:50
5	7145	((250/281,282).CCLS.) or ((438/745).CCLS.) or ((436/43,47).CCLS.) or ((134/2,10,22.14,32,48,71,79,80).CCLS.)	USPAT; US-PGPUB	2003/11/25 10:51
6	1	((250/281,282).CCLS.) or ((438/745).CCLS.) or ((436/43,47).CCLS.) or ((134/2,10,22.14,32,48,71,79,80).CCLS.)) and ((wafer near4 contaminat\$5 near4 edge) with solvent)	USPAT; US-PGPUB	2003/11/25 10:53
7	4	((250/281,282).CCLS.) or ((438/745).CCLS.) or ((436/43,47).CCLS.) or ((134/2,10,22.14,32,48,71,79,80).CCLS.)) and ((wafer near4 contaminat\$5) with solvent)	USPAT; US-PGPUB	2003/11/25 10:53

	U	1	Docum nt ID	Issue Date	Pages	Title	Current OR
1	<input type="checkbox"/>	<input type="checkbox"/>	US 20030108823 A1	20030612	26	Method and apparatus for removing organic films	430/329
2	<input type="checkbox"/>	<input type="checkbox"/>	US 20030017419 A1	20030123	40	Mass production method of semiconductor integrated circuit device and manufacturing method of electronic device	430/311
3	<input type="checkbox"/>	<input type="checkbox"/>	US 20020153482 A1	20021024	6	Method and apparatus for detecting contaminating species on a wafer edge	250/281
4	<input type="checkbox"/>	<input type="checkbox"/>	US 5498293 A	19960312	7	Cleaning wafer substrates of metal contamination while maintaining wafer smoothness	134/3

[illegible]

	Image Doc. Displayed	PT
1	US 20030108823	<input type="checkbox"/>
2	US 20030017419	<input type="checkbox"/>
3	US 20020153482	<input type="checkbox"/>
4	US 5498293	<input type="checkbox"/>